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**C**O

Infineon on the Move to Asia

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Never stop thinking.



### Disclaimer

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## Asia on the Move



#### Current:

- Asia Pacific (Singapore/Hong Kong)
- Japan (Tokyo)



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### Asia on the Move



New

Zealand

Transition (1 - 2 years)

- Japan (Tokyo)
- China (Shanghai)
- Rest of Asia Pacific (Singapore)





### Asia on the Move

• Rest of Asia Pacific (Singapore)



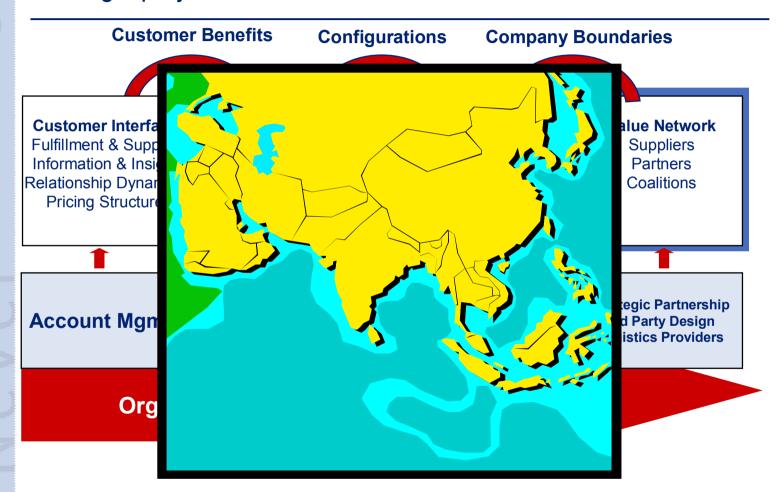
New

Zealand

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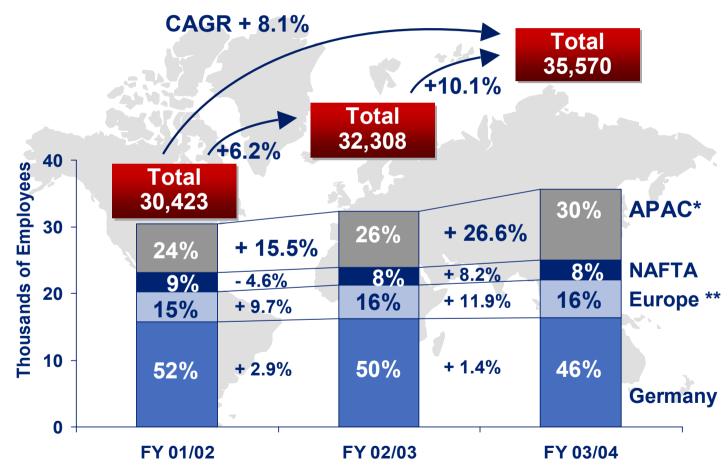
## Strategic projects - Asia as a lead market



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### Infineon's shift of headcount towards Asia Pacific



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<sup>\*</sup> Including Japan and RoW

<sup>\*\*</sup> Excluding Germany



## The Chinese market offers a unique opportunity

### Attractiveness based upon ...

(1) The Compound Annual Growth Rate (CAGR) from 2001 through 2004 for ...

... Americas IC Market\* 14% ... China's IC Market 46%

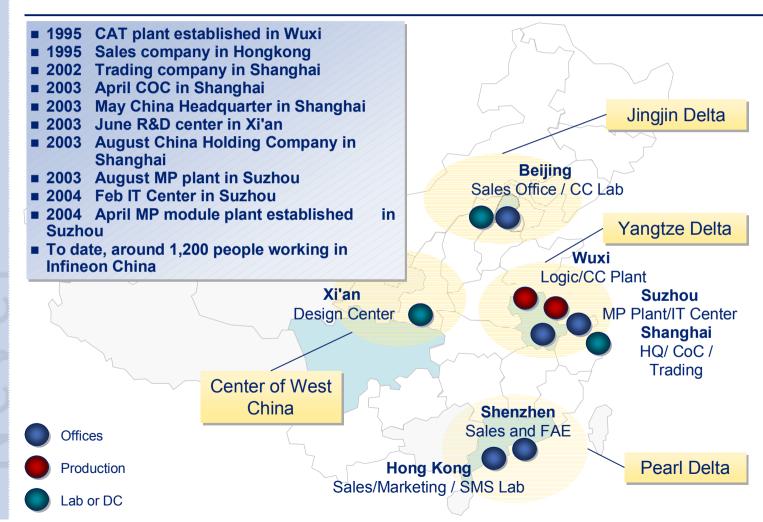
(2) The worldwide IC industry is expected to face a 2% decline in 2005. China's IC market, however, is expected to grow 11% to \$34.3 billion in 2005. Therewith China is forecast to represent 20% of the world's 2005 \$175.4 billion in IC consumption.

(3) The Chinese IC market forecast for 2010 is \$95 billion.

<sup>\*</sup> Note: As recently as 2001, the Americas IC market was more than three times the size of China's IC market Source: EE Times. 2005



### Infineon's business development in China



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# Case study: R&D Infineon's decision for development center in Xi'an

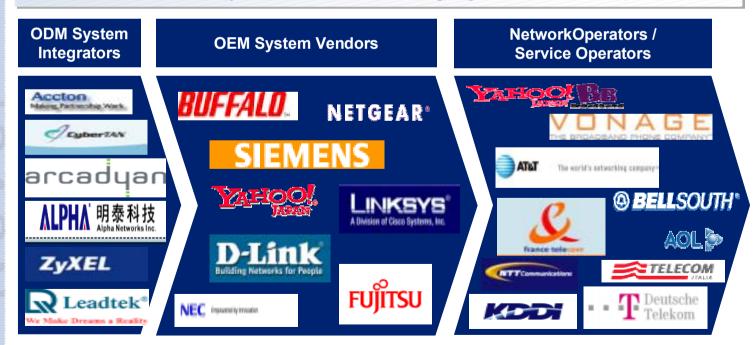
- Based upon thorough analysis and rating criteria, clear pro's and con's could be identified for all different options.
- One of the main reasons for Infineon Technologies to choose Xi'an was its
   IC industrial and software base.
- In addition to this, Xi'an has a large IC talent pool offering an extremely high number of highly qualified students.
- Furthermore, both turn over rate and labor costs are relatively low.
- Finally, Xi'an, as an amazing city rich of history and culture, would offer IFX staff both attractive work- and life conditions.
- More than 1,000 engineers planned by 2007.
- First product development activities started for memory products.





# Case study: following the supply chain Global project management for CPE business

- Acquisition of Taiwan-based AMDtek in 2004 due to strong local technical competence.
- Majority of all CPE boxes worldwide manufactured in Taiwan.
- Infineon serves the whole value chain: from innovations at local ODMs via OEM system vendors through global service operators.



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# Case study: roll-out of digital terrestrial TV for mobile phones in South Korea

- Infineon is market leader in the fast growing digital terrestrial tuner market (DVB-T standard).
- Our tuner IC products are used in most digital terrestrial standard TV sets, Set-Top-Boxes and world's first PCMCIA card for TV reception.
- We intend to leverage this strong position into a complete DVB-H / T-DMB frontend solution.
- Infineon to participate in the world's first roll-out of mobile TV in South Korea in 2005 with a tuner IC in a DMB-receiving mobile phone from LG Electronics.



World's first terrestrial DMBreceiving mobile phone from LG Electronics\*

T-DMB (Terrestrial-Digital Mobile Broadcasting, Mobile TV standard in Korea)

<sup>\*</sup> Source: www.lge.com, Nov. 15, 2004



# Case study: power logic manufacturing Why a new logic fab for AIM?

- Power semiconductors face a strong and stable long-term growth.
- In-house capacity increase is required for AIM due to volume growth and lack of vital external partnership model.
- Power semiconductors cannot be shrunk as fast as memory or standard logic technologies. Therefore, output increase per fab is almost not possible.
- Low cost site is favorable over mid-term due to much lower labor costs.
- Kulim High-Tech Park in Malaysia is chosen as the new fab's location resulting out of a thorough site selection process.



# Case study: power logic manufacturing Key figures of Malaysia fab for power semiconductors

#### **Technology**

■ feature sizes of 0.35µm, 0.5µm, 0.7µm and 1.0µm

# Capacity & Facility

- Capacity of about 100k WSPM on 8-inch wafers
- 2 modules, each 5.000 m<sup>2</sup> clean-room (class 10, Litho class 1)
- 1700 employees (1170 direct functions, 530 engineers/admin.)

#### Site

- Kulim High-Tech Park, Kedah Malaysia
- Size of land plot 200.000 m<sup>2</sup>

#### **Investment**

■ Total investment of about € 1bn

#### **Timeline**

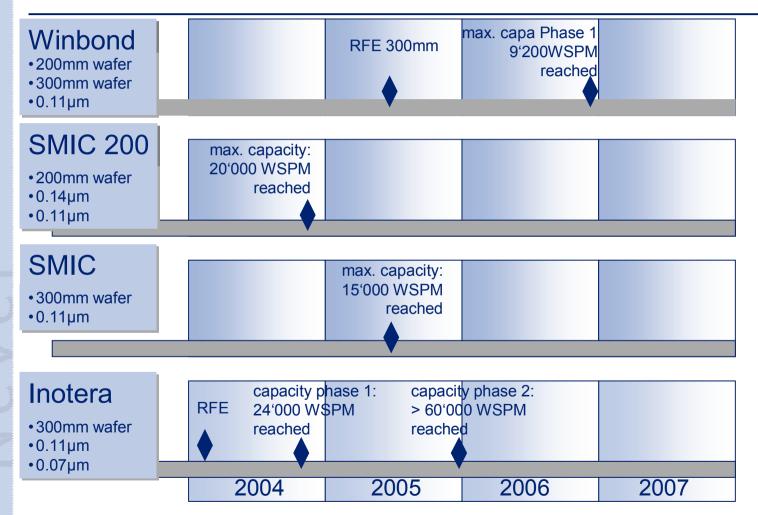
- Decision making Nov 2004
- Ground breaking Feb 2005
- Equipment move-in and start of transfer Feb 2006
- Full fab capacity reached

end 2009

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# Case study: DRAM frontend manufacturing partners Milestones at DRAM cooperation partners in Asia



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# Case study: DRAM frontend manufacturing partners DRAM manufacturing shift towards Asia Pacific



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# Case study: DRAM frontend manufacturing partners Alliances with Inotera and NanYa





- Investment of about USD 2.2 bn
- Capacity of 24,000 WSPM reached
   2 months ahead of schedule in
   October 2004
- 300mm capacity of > 60,000 WSPM by early 2006
- First products: 256M DDR and 512M DDR2 in 110nm technology
- Largest DRAM manufacturing module worldwide when completed early 2006

# Memory development center in Dresden

- Approximately 400 employees including 50 from NanYa
- Technology: DRAM 90nm and 70nm
- Focusing development in 300mm line





# Case study: DRAM backend manufacturing partner Backend manufacturing in China: Suzhou

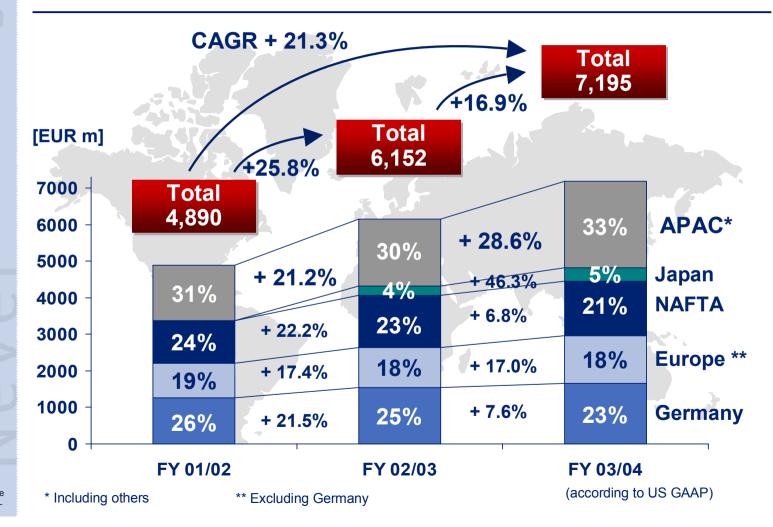


- Investment of about US\$ 1 billion planned in total
- Official opening in September 2004
- Shipment qualification for components and modules achieved by end 2004
- Maximum capacity planned of up to 1billion chips per year
- More than 1,000 employees planned when completely ramped
- First products: 256M DDR in BGA packages and related modules

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## APAC activities major driver of Infineon growth story



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## Globalisation



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### Globalisation

Think Global .... Trust Local Trust Global .... Act Local

Stopth

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